IEC 62769-8

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INTERNATIONAL STANDARD

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Field device integration (FDI®) – Part 8: EDD to OPC-UA Mapping

Intégration des appareils de terrain (FDI®) – Partie 8: Mapping de l'EDD avec l'OPC-UA

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FIELD DEVICE INTEGRATION (FDI®) –

Part 8: EDD to OPC-UA Mapping

FOREWORD

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The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/851/CDV	65E/909/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI®)*, can be found on the IEC website.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 8: EDD to OPC-UA Mapping

1 Scope

This part of IEC 62769 specifies how the internal view of a device model represented by the EDD can be transferred into an external view as an OPC-UA information model by mapping EDD constructs to OPC-UA objects.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE For undated references, the edition of the referenced document (including any amendments), which applies for a specific FDI®[1] Technology Version is defined within the FDI® Technology Management Document and on the support portals of FieldComm Group and PI International.

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) − Part 3: EDDL syntax and semantics*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-8, *OPC Unified Architecture – Part 8: Data Access*

IEC 62541-9:2020, *OPC Unified Architecture – Part 9: Alarms and Conditions*

OPC 10000-17, *OPC Unified Architecture – Part 17: Alias Names*

OPC 10000-19, *OPC Unified Architecture – Part 19: Dictionary Reference*

IEC 62541-100, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-5, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

IEC 62769-6, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

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